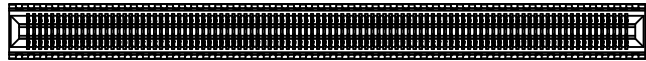
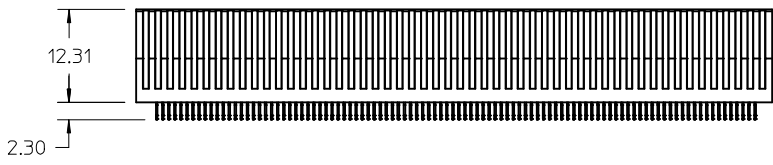


PART NUMBER	VERSION	BAY 1/BAY 2	TOTAL CIRCUITS	DIM A	SALES DRAWING (SEE NOTE 8)
170673-2278	2 BAY	146/132	278	118.63	SD-170673-2278
170673-1200	1 BAY	200	200	84.20	SD-170673-1200
170673-2108	2 BAY	86/22	108	50.63	SD-170673-2108
170673-2080	2 BAY	52/28	80	39.43	SD-170673-2080
170673-1046	1 BAY	46	46	22.60	SD-170673-1046

2 BAY EDGELINE

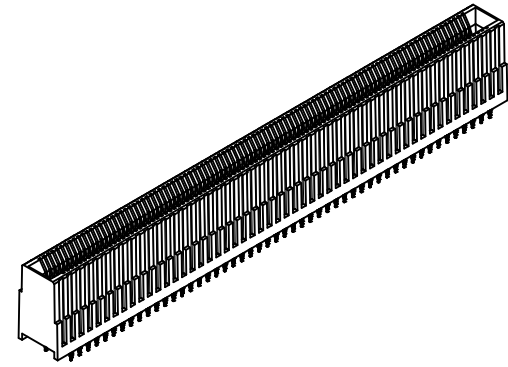
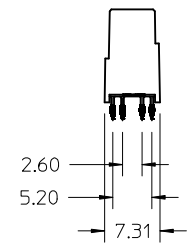


1 BAY EDGELINE



LAST CIRCUIT

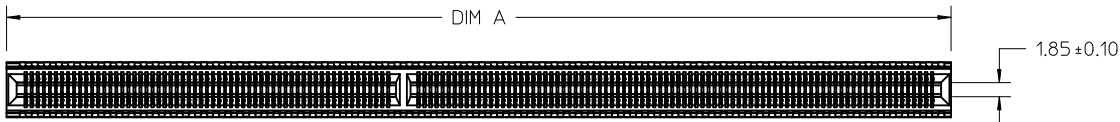
FIRST CIRCUIT



NOTES:

- MATERIAL:
HOUSING - GLASS FILLED THERMOPLASTIC, 94-V0, BLACK
TERMINALS - COPPER ALLOY
- FINISH:
CONTACT AREA: HARD GOLD -0.76μm MIN OVER 3.80μ NICKEL
COMPLIANT AREA: TIN - 0.76/1.52μm OVER NICKEL
- REFER TO PS-75594-999 PRODUCT SPECIFICATION FOR ALL ELECTRICAL, MECHANICAL AND ENVIRONMENTAL SPECIFICATIONS.
- PROCESSING: PRESSFIT TO PC BOARD.
- MATING PC BOARD THICKNESS = 1.60±0.16MM OVER CONTACT PADS.
- PRODUCT IS ELV AND RoHS COMPLIANT. LEVEL OF COMPLIANCE: 6/6
ALL BANNED SUBSTANCES ARE REMOVED:
Pb (LEAD)
HEXAVALENT CHROMIUM (CrVI)
CADMIUM
MERCURY
POLYBROMINATED BIPHENYL (PBB)
POLYBROMINATED DIPHENYL ETHER (PBDE)
- THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPEC PS-45499-002
- FOR EDGE CARD AND MOUNTING PCB LAYOUT DETAIL SEE CORRESPONDING SALES DRAWING.

RELEASED REV A EC NO: UCP2011-2702 DRWNG: DROSCA 2011/03/07 CHKD: JCOMERCI 2011/03/28 APPR: JCOMERCI 2011/03/28	DESCRIPTION REV 0 0 0	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
			mm INCH	DRAWN BY DATE DROSCA 2010/06/22	TITLE EDGELINE 12.5GB 0.062*PCB 0.8MM PITCH		
			4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± --- ± --- 1 PLACE ± --- ± ---	CHECKED BY DATE JCOMERCI 2010/06/22			
			ANGULAR ±1/2°	APPROVED BY DATE JCOMERCI 2010/10/25			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-170673-0001	SHEET NO. 1 OF 1		
			SIZE C	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

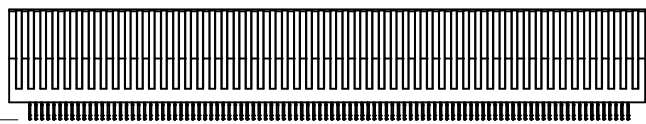


PART NUMBER	VERSION	BAY 1/BAY 2	TOTAL CIRCUITS	DIM A	SALES DRAWING (SEE NOTE 8)
170673-2278	2 BAY	146/132	278	118.63	SD-170673-2278
170673-1200	1 BAY	200	200	84.20	SD-170673-1200
170673-2108	2 BAY	86/22	108	50.63	SD-170673-2108
170673-2080	2 BAY	52/28	80	39.43	SD-170673-2080
170673-1046	1 BAY	46	46	22.60	SD-170673-1046

2 BAY EDGELINE

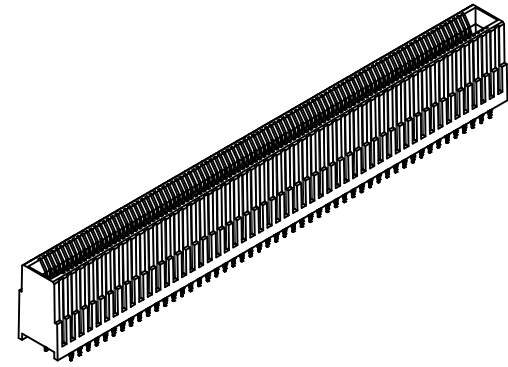
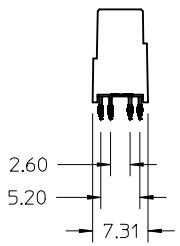


1 BAY EDGELINE



LAST CIRCUIT

FIRST CIRCUIT

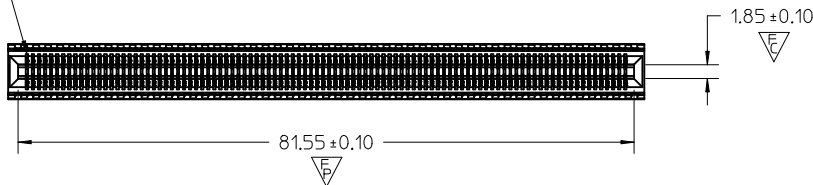


NOTES:

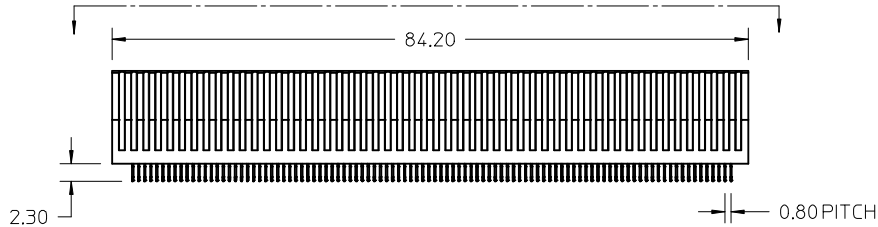
- MATERIAL:
HOUSING - GLASS FILLED THERMOPLASTIC, 94-V0, BLACK
TERMINALS - COPPER ALLOY
- FINISH:
CONTACT AREA: HARD GOLD -0.76μm MIN OVER 3.80μ NICKEL
COMPLIANT AREA: TIN - 0.76/1.52μm OVER NICKEL
- REFER TO PS-75594-999 PRODUCT SPECIFICATION FOR ALL ELECTRICAL, MECHANICAL AND ENVIROMENTAL SPECIFICATIONS.
- PROCESSING: PRESSFIT TO PC BOARD.
- MATING PC BOARD THICKNESS = 1.60±0.16MM OVER CONTACT PADS.
- PRODUCT IS ELV AND RoHS COMPLIANT. LEVEL OF COMPLIANCE: 6/6
ALL BANNED SUBSTANCES ARE REMOVED:
Pb (LEAD)
HEXAVALENT CHROMIUM (CrVI)
CADMIUM
MERCURY
POLYBRMINATED BIPHENYL (PBB)
POLYBROMINATED DIPHENYL ETHER (PBDE)
- THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPEC PS-45499-002
- FOR EDGECARD AND MOUNTING PCB LAYOUT DETAIL SEE CORRESPONDING SALES DRAWING.

RELEASED REV A EC NO: UCP2011-2702 DRWNG: DROSCA 2011/03/07 CHKD: JCOMERCI 2011/03/28 APPR: JCOMERCI 2011/03/28	DESCRIPTION REV: A	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
		▽ = 0	mm INCH	MM ONLY	2:1	METRIC	
		▽ = 0	4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± --- ± --- 1 PLACE ± --- ± ---	DRAWN BY DATE DROSCA 2010/06/22 CHECKED BY DATE JCOMERCI 2010/06/22 APPROVED BY DATE JCOMERCI 2010/10/25	TITLE	EDGELINE 12.5GB 0.062"PCB 0.8MM PITCH	
▽ = 0	ANGULAR ±1/2°	MATERIAL NO.	SEE TABLE		DOCUMENT NO.	MOLEX INCORPORATED	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
							SHEET NO. 1 OF 1

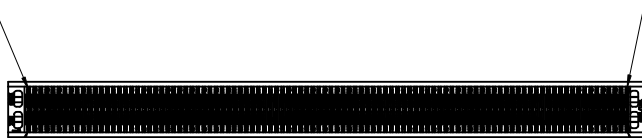
CIRCUIT #1



PIN-OUT VIEW



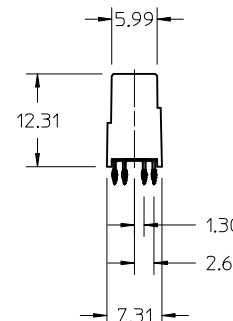
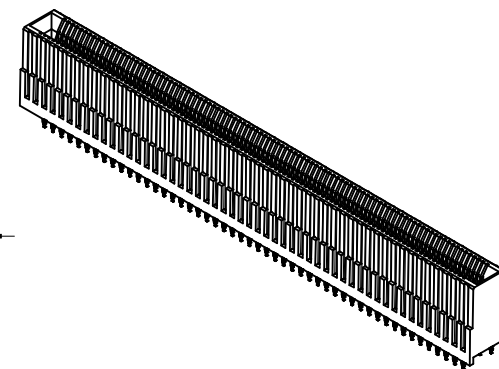
CIRCUIT #200



CIRCUIT #1

CIRCUIT #101

CIRCUIT #100

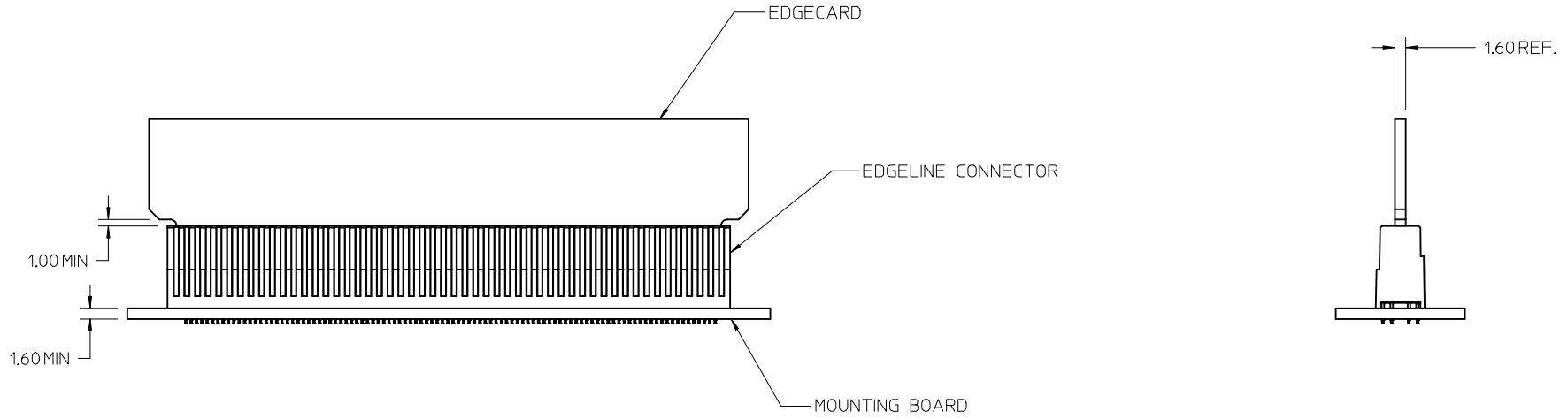


NOTES:

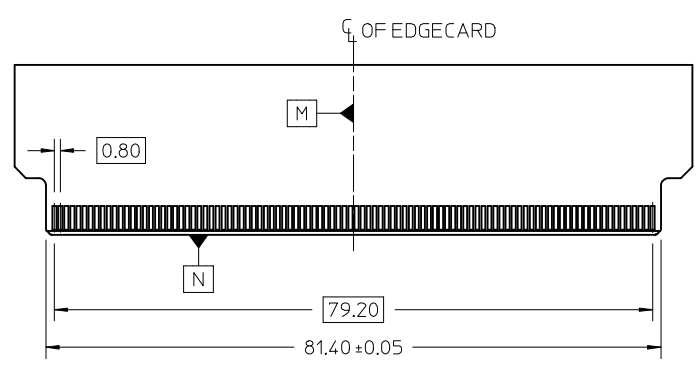
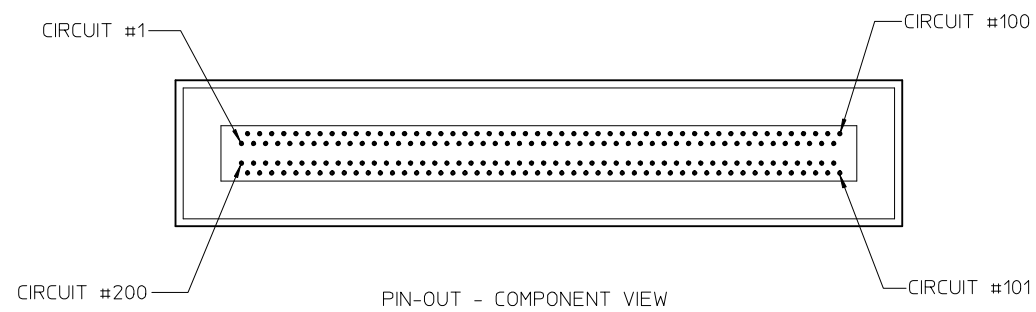
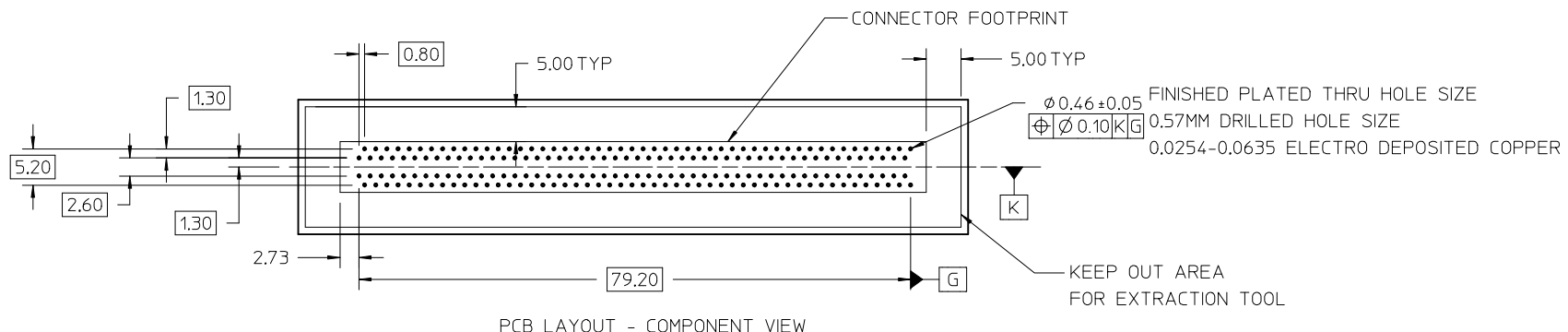
- MATERIAL:
HOUSING - GLASS FILLED THERMOPLASTIC, 94-VO, BLACK
TERMINALS - COPPER ALLOY
- FINISH:
CONTACT AREA: HARD GOLD -0.76μm MIN OVER 3.80μ NICKEL
COMPLIANT AREA: TIN - 0.76/1.52μm OVER NICKEL
- REFER TO PS-75594-999 PRODUCT SPECIFICATION FOR ALL ELECTRICAL, MECHANICAL AND ENVIRONMENTAL SPECIFICATIONS.
- REFER TO PK-76693-900 FOR ALL PACKAGING SPECIFICATIONS.
- PROCESSING: PRESSFIT TO PC BOARD.
- MATING PC BOARD THICKNESS = 1.60±0.16MM OVER CONTACT PADS.
- THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPEC PS-45499-002

CORRECT EDGE CARD WIDTH TOLERANCE IEC NO: UCP2016-4620 DRAWINGS 2016/06/02 CHKD: APPR:DMC/GOMAN 2016/06/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM ONLY	2:1	METRIC	☐
	▽=1	4 PLACES ± --- ± ---	DRAWN BY DATE	TITLE		
	▽=1	3 PLACES ± --- ± ---	GES 2014/09/26	EDGE LINE 12.5GB 200CKTS 0.062"PCB 0.8MM PITCH		
		2 PLACES ± 0.13 ± ---	CHECKED BY DATE	APPROVED BY DATE		
		1 PLACE ± 0.25 ± ---	MATERIAL NO. 1706731200			
		0 PLACE ± --- ± ---	DOCUMENT NO. SD-170673-1200			
		ANGULAR ± 2 °	SHEET NO. 1 OF 4			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

EDGE LINE CONNECTOR BOARD MOUNTING

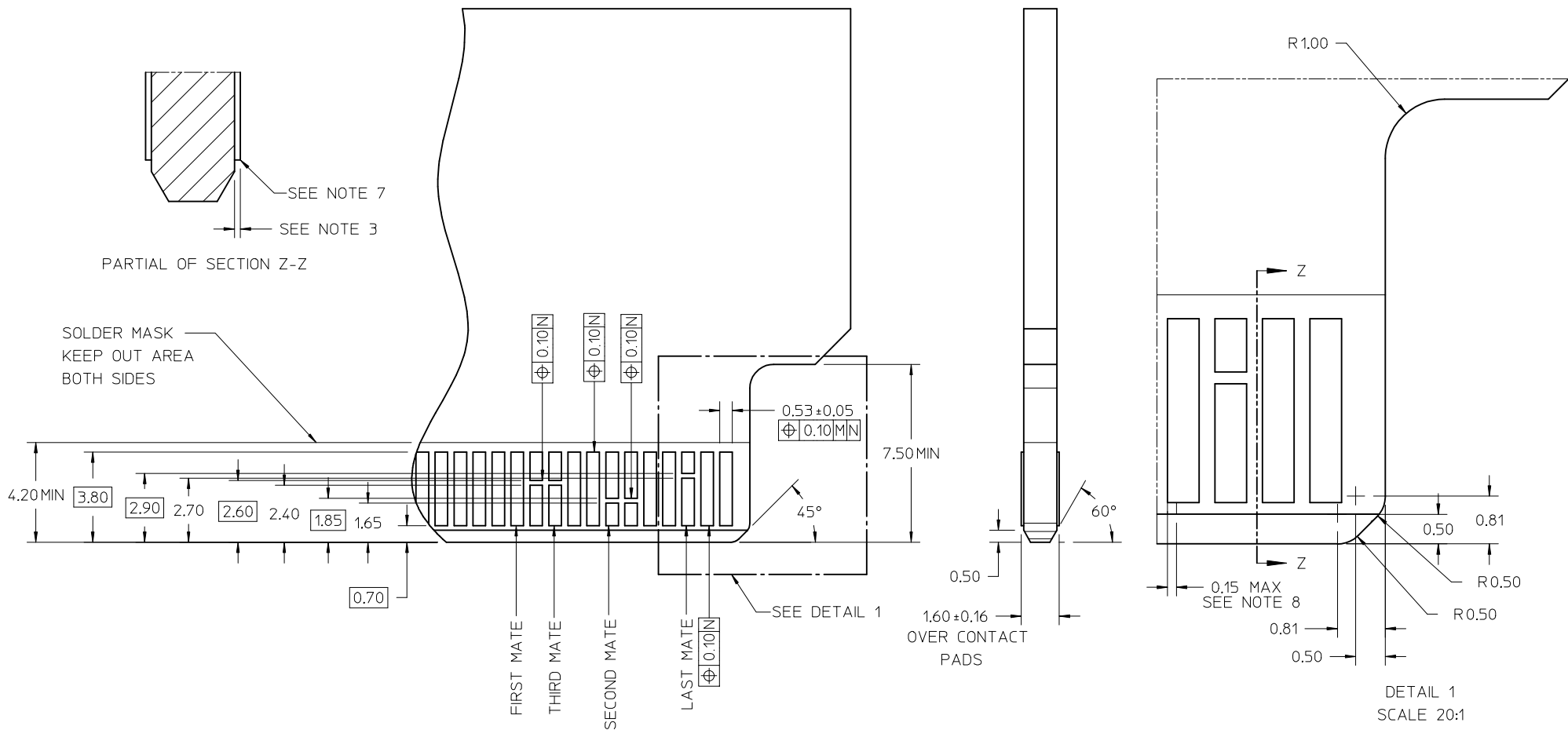


SEE SHEET 1 EC NO: UCP2016-4620 2016/06/02 DRWNGES CHKD: APPR:DMCGOWAN 2016/06/13 DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	∇=0 ∇=0 ∇=0	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.13 ± --- 1 PLACE ± 0.25 ± --- 0 PLACE ± --- ± ---	MM ONLY	2:1	METRIC	DRAWN BY DATE GES 2014/09/26 CHECKED BY DATE APPROVED BY DATE
	ANGULAR ± 2 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO.	DOCUMENT NO.	TITLE EDGE LINE 12.5GB 200CKTS 0.062*PCB 0.8MM PITCH		SHEET NO. 2 OF 4
	SIZE C THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	SEE SHEET 1	SD-170673-1200	molex		



SEE SHEET 1 EC NO: UCP2016-4620 DRWNGES 2016/06/02 CHKD: APPR:DMCGOWAN 2016/06/13 REV:	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$\nabla = 0$	mm INCH	MM ONLY	2:1	METRIC	
	$\nabla = 0$	4 PLACES ± --- ± ---	DRAWN BY DATE	TITLE		
	$\nabla = 0$	3 PLACES ± --- ± ---	GES 2014/09/26	EDGE LINE 12.5GB 200CKTS 0.062*PCB 0.8MM PITCH		
		2 PLACES ± 0.13 ± ---	CHECKED BY DATE	APPROVED BY DATE		
		1 PLACE ± 0.25 ± ---	MATERIAL NO. SEE SHEET 1			
		0 PLACE ± --- ± ---	DOCUMENT NO. SD-170673-1200			
		ANGULAR ± 2 °	SHEET NO. 3 OF 4			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

MODULE EDGE CARD CONTACT DETAIL

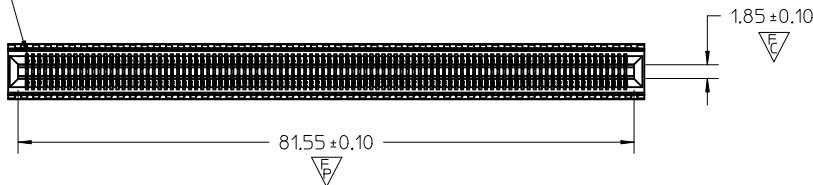


MATING PCB NOTES:

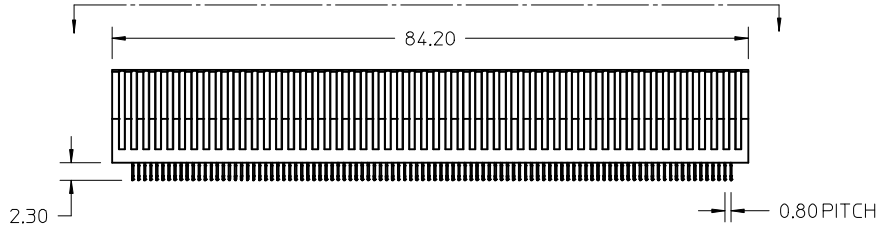
- CONNECTOR LAND CONDITIONS SHALL MEET THE MOST CURRENT REVISION OF PCB SPECIFICATION IPC-6012C-2010 SECTION 3.5.4.4.
- DIMENSIONS APPLY TO LANDS ON BOTH SIDES OF THE BOARD.
- THE THICKNESS OF THE OUTER METAL LAYERS, INCLUDING FOIL, COPPER PLATING, AND THE PROTECTIVE SURFACE FINISH, SHALL BE 0.066mm MAX.
- CHAMFER ROUGHNESS NOT TO EXCEED 3.17 MICROMETERS.
- CHAMFER PROCESS SHALL NOT DAMAGE THE GOLD EDGE LANDS.
- EDGE CARD CHAMFER NOT TO GO THRU GOLD LANDS.
- 0.03mm MAX PLATING OVERHANG ON ALL GOLD LAND EDGES.
- MOLEX RECOMMENDS NO TIE-BARS ON THE LEADING EDGE OF THE GOLD LAND. IF TIE-BARS ARE USED, THEY SHALL BE PLACED TO ONE SIDE OF THE GOLD LAND. APPLIES TO ALL GOLD LANDS.

SEE SHEET 1 EC NO: UCP2016-4620 DRWNGES 2016/06/02 CHKD: JAPPR:DMCGOWAN 2016/06/13 APPR:	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 8:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	▽=0	mm INCH	DRAWN BY GES	DATE 2014/09/26	TITLE EDGELINE 12.5GB 200CKTS 0.062"PCB 0.8MM PITCH	
	▽=0	4 PLACES ± --- ± ---	CHECKED BY	DATE	molex DOCUMENT NO. SD-170673-1200	
	▽=0	3 PLACES ± --- ± ---	APPROVED BY	DATE		
		2 PLACES ± 0.13 ± ---	MATERIAL NO. SEE SHEET 1			
		1 PLACE ± 0.25 ± ---	SIZE C		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
		0 PLACE ± --- ± ---				
		ANGULAR ± 2 °				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				

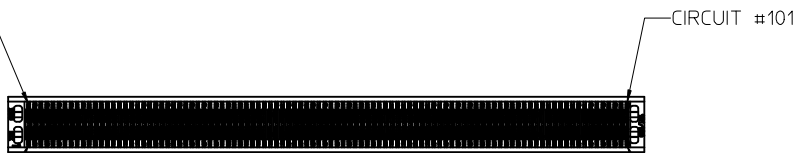
CIRCUIT #1



PIN-OUT VIEW

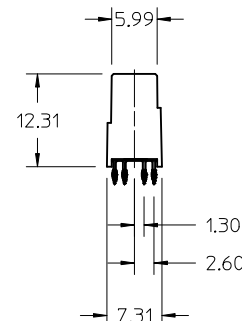
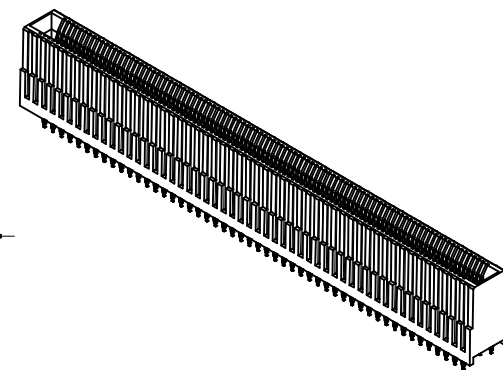


CIRCUIT #200



CIRCUIT #1

CIRCUIT #100

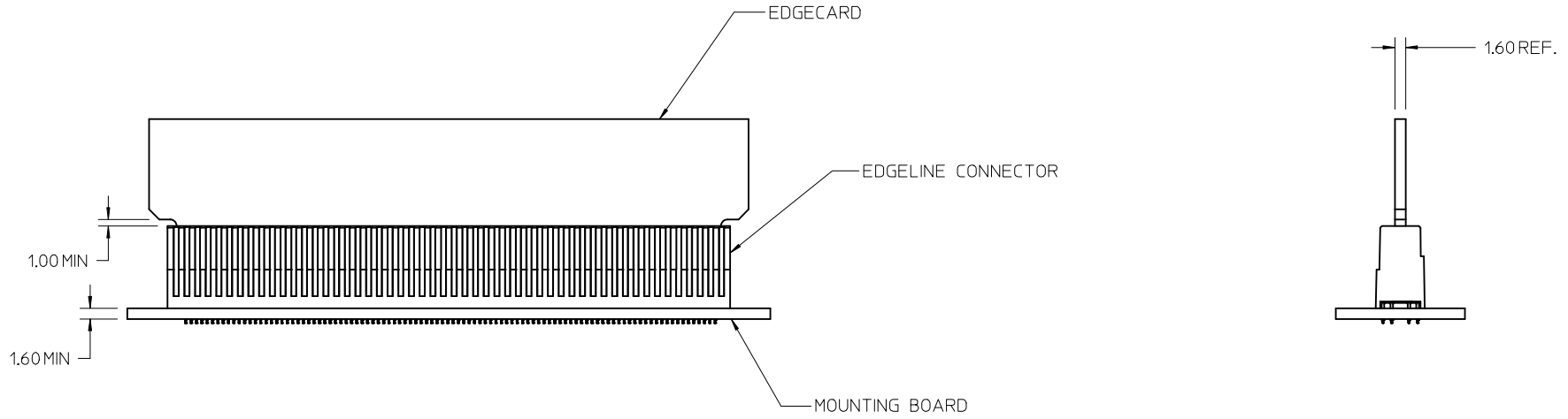


NOTES:

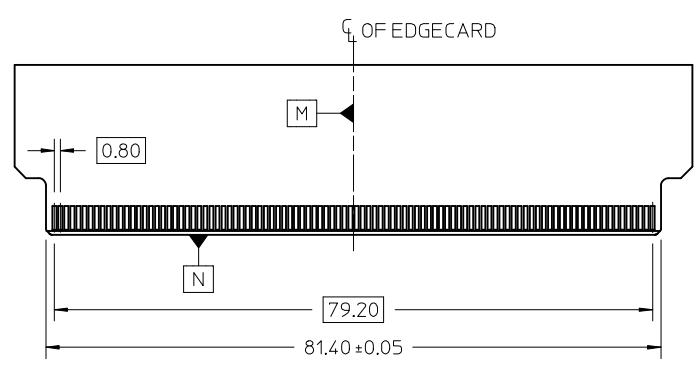
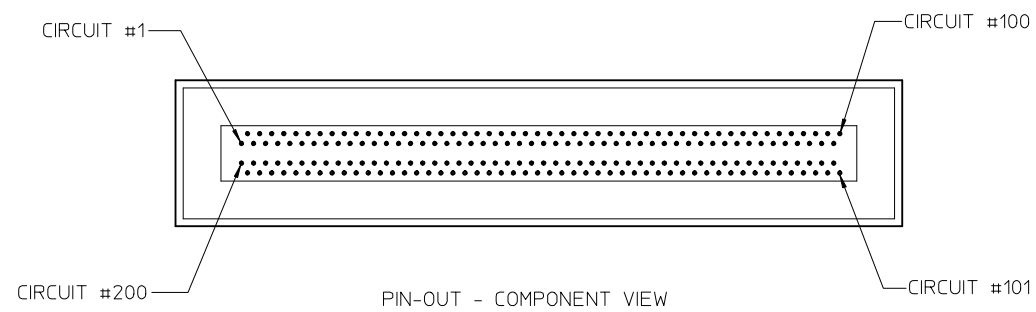
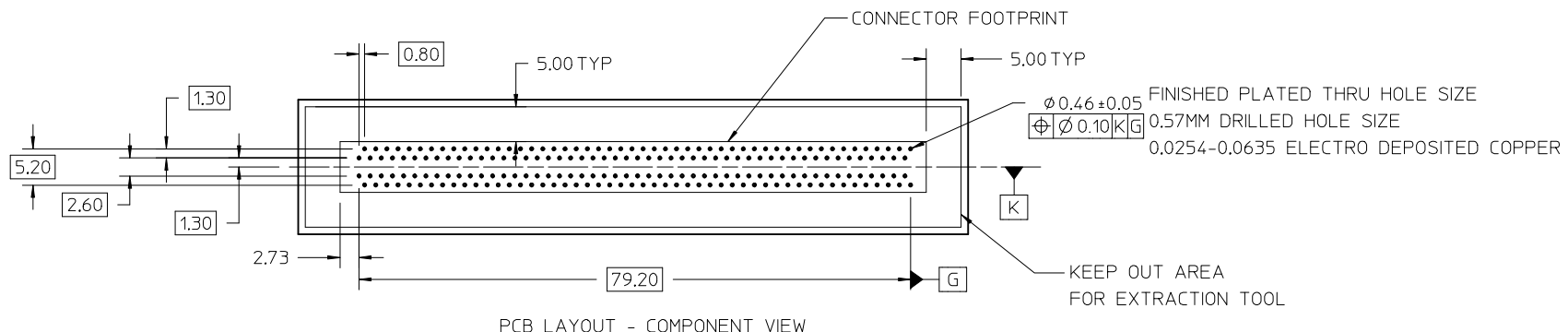
1. MATERIAL:
HOUSING - GLASS FILLED THERMOPLASTIC, 94-VO, BLACK
TERMINALS - COPPER ALLOY
2. FINISH:
CONTACT AREA: HARD GOLD -0.76µm MIN OVER 3.80µ NICKEL
COMPLIANT AREA: TIN - 0.76/1.52µm OVER NICKEL
3. REFER TO PS-75594-999 PRODUCT SPECIFICATION FOR ALL ELECTRICAL, MECHANICAL AND ENVIRONMENTAL SPECIFICATIONS.
4. REFER TO PK-76693-900 FOR ALL PACKAGING SPECIFICATIONS.
5. PROCESSING: PRESSFIT TO PC BOARD.
6. MATING PC BOARD THICKNESS = 1.60±0.16MM OVER CONTACT PADS.
7. THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPEC PS-45499-002

CORRECT EDGE CARD WIDTH TOLERANCE IEC NO: UCP2016-4620 DRWINGS 2016/06/02 CHKD: APPR:DMC/GOMAN 2016/06/13 REV:	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM ONLY	2:1	METRIC	☐
	▽=1	4 PLACES ± --- ± ---	DRAWN BY DATE	TITLE EDGELINE 12.5GB 200CKTS 0.062*PCB 0.8MM PITCH		
	▽=1	3 PLACES ± --- ± ---	GES 2014/09/26			
	2 PLACES ± 0.13 ± ---	CHECKED BY DATE	MATERIAL NO. DOCUMENT NO. SHEET NO. 1706731200 SD-170673-1200 1 OF 4			
	1 PLACE ± 0.25 ± ---	APPROVED BY DATE				
	0 PLACE ± --- ± ---	ANGULAR ± 2 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

EDGE LINE CONNECTOR BOARD MOUNTING

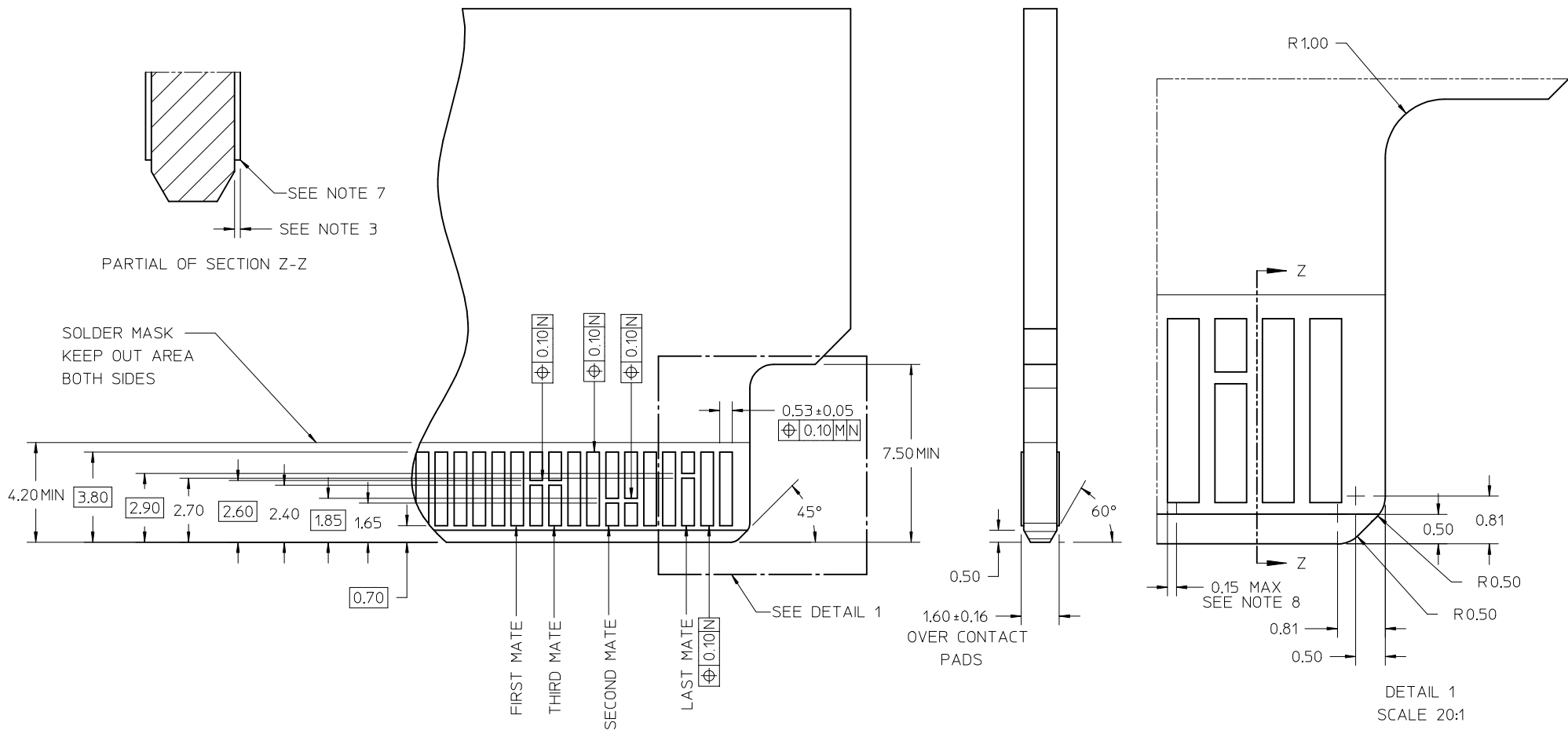


SEE SHEET 1 EC NO: UCP2016-4620 2016/06/02 DRWNGES CHKD: APPR:DMCGOWAN 2016/06/13 DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.13 ± --- 1 PLACE ± 0.25 ± --- 0 PLACE ± --- ± ---	mm INCH ± --- ± --- ± --- ± --- ± 0.13 ± --- ± 0.25 ± --- ± --- ± ---	DRAWN BY GES DATE 2014/09/26 CHECKED BY DATE APPROVED BY DATE	TITLE EDGE LINE 12.5GB 200CKTS 0.062*PCB 0.8MM PITCH			
	ANGULAR ± 2 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE SHEET 1	DOCUMENT NO. SD-170673-1200	SHEET NO. 2 OF 4		
	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



SEE SHEET 1 EC NO: UCP2016-4620 DRWNGES 2016/06/02 CHKD: APPR:DMCGOWAN 2016/06/13 REV:	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$\nabla=0$	mm INCH		MM ONLY	2:1	METRIC	
	$\nabla=0$	4 PLACES ± ---	± ---	DRAWN BY	DATE	TITLE	
	$\nabla=0$	3 PLACES ± ---	± ---	GES	2014/09/26	EDGELINE 12.5GB 200CKTS 0.062*PCB 0.8MM PITCH	
		2 PLACES ± 0.13	± ---	CHECKED BY	DATE	APPROVED BY	
		1 PLACE ± 0.25	± ---	APPROVED BY		DATE	
		0 PLACE ± ---	± ---	MATERIAL NO.		DOCUMENT NO.	SHEET NO.
		ANGULAR ± 2 °		SEE SHEET 1		SD-170673-1200	3 OF 4
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

MODULE EDGE CARD CONTACT DETAIL



MATING PCB NOTES:

- CONNECTOR LAND CONDITIONS SHALL MEET THE MOST CURRENT REVISION OF PCB SPECIFICATION IPC-6012C-2010 SECTION 3.5.4.4.
- DIMENSIONS APPLY TO LANDS ON BOTH SIDES OF THE BOARD.
- THE THICKNESS OF THE OUTER METAL LAYERS, INCLUDING FOIL, COPPER PLATING, AND THE PROTECTIVE SURFACE FINISH, SHALL BE 0.066mm MAX.
- CHAMFER ROUGHNESS NOT TO EXCEED 3.17 MICROMETERS.
- CHAMFER PROCESS SHALL NOT DAMAGE THE GOLD EDGE LANDS.
- EDGE CARD CHAMFER NOT TO GO THRU GOLD LANDS.
- 0.03mm MAX PLATING OVERHANG ON ALL GOLD LAND EDGES.
- MOLEX RECOMMENDS NO TIE-BARS ON THE LEADING EDGE OF THE GOLD LAND. IF TIE-BARS ARE USED, THEY SHALL BE PLACED TO ONE SIDE OF THE GOLD LAND. APPLIES TO ALL GOLD LANDS.

SEE SHEET 1 EC NO: UCP2016-4620 DRWNGES 2016/06/02 CHKD: JAPPR:DMCGOWAN 2016/06/13 APPR:	QUALITY SYMBOLS ∇=0 ∇=0 ∇=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 8:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.13 ± --- 1 PLACE ± 0.25 ± --- 0 PLACE ± --- ± ---	mm INCH DRAWN BY DATE GES 2014/09/26 CHECKED BY DATE APPROVED BY DATE	TITLE EDGELINE 12.5GB 200CKTS 0.062"PCB 0.8MM PITCH	MATERIAL NO. SEE SHEET 1	DOCUMENT NO. SD-170673-1200	SHEET NO. 4 OF 4
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					